

L Number	Hits	Search Text	DB	Time stamp
1	0	("(slder adj mask) with (comprising or material)").PN.	USPAT	2002/06/04 11:15
2	702	(solder adj mask) with (comprising or material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 11:16
3	333	((solder adj mask) with (comprising or material)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 11:42
4	3	"3004545"	JPO; DERWENT	2002/06/04 11:46
5	1	("5959363").PN.	USPAT	2002/06/04 11:52
6	1	("3871014").PN.	USPAT	2002/06/04 11:59
7	1804	(solder adj mask) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 12:17
8	198	((solder adj mask) and substrate) and (mask with (opening or gap or space or shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 12:06
9	7	((solder adj mask) near chip) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 12:23
10	140	((solder adj mask) with chip) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 13:11
11	133	((solder adj mask) with chip) and substrate) not ((solder adj mask) near chip) and substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 12:26
12	200	(captured or capture) adj (pad or pads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 13:03
13	93	((captured or capture) adj (pad or pads)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 12:32
14	13	(chip or die) with ((captured or capture) adj (pad or pads))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 12:52
15	22	(chip or die) with (((solder adj mask) or (polymer or ployimide)) near (pad or pads))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 12:58
16	8	((captured or capture) adj (pad or pads)) with (advantage or benefit or increase or enhance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 13:04

17	815	((solder adj mask) or polymeric or polymer) with (pad or pads)) same (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 13:13
18	90	((solder adj mask) with (pad or pads)) with (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 13:17
19	2	("5327013" "5977632").PN.	USPAT	2002/06/04 13:15
20	112	(solder adj mask) with ((chip or die) and (pad or pads))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 13:21
21	76	257/778.ccls. and (solder adj mask)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/04 13:24